

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) An abrasive slurry having dispersion stability, ~~comprising~~
consisting essentially of:

abrasive fine particles made of one or more kinds of oxides;

colloidal fine particles made of colloidal oxide with an average particle size smaller than
an average particle size of the abrasive fine particles; and

a dispersion medium in which the abrasive fine particles and the colloidal fine particles
are dispersed;

wherein the average particle size (Dp) of the abrasive fine particles is 100 to 5,000 nm,
the average particle size (Dc) of the colloidal fine particles is 10 to 300 nm, and a particle size
ratio (Dc/Dp) of the average particle size (Dc) of the colloidal fine particles to the average
particle size (Dp) of the abrasive fine particles is 10 or less, and the abrasive fine particles have a
particle concentration (Cp) of 5 to 30 wt%, the colloidal fine particles have a particle
concentration (Cc) of 0.1 to 5 wt%, and a weight distribution ratio (Cc/Cp) of the particle
concentration (Cc) of the colloidal fine particles to the particle concentration (Cp) of the abrasive
fine particles is 1 or less.

2-3. (Cancelled)

4. (Currently Amended) ~~An~~ The abrasive slurry having dispersion stability according to
claim 1, wherein the dispersion medium comprises water or an aqueous dispersion medium
mainly containing water.

5. (Currently Amended) ~~A~~ The abrasive slurry having dispersion stability according to claim 1, wherein the abrasive fine particles comprise a cerium oxide particle.

6. (Currently Amended) ~~A~~ The abrasive slurry having dispersion stability according to claim 1, wherein the colloidal fine particles comprise a colloidal silica.

7. (Previously Presented) A manufacturing method for a substrate as an inorganic substrate, comprising polishing the substrate using the abrasive slurry according to claim 1.

8. (Currently Amended) A The manufacturing method for a substrate according to claim 7, wherein the substrate has a surface on which an oxide film is formed.

9. (Currently Amended) ~~A~~ The abrasive slurry having dispersion stability according to any one of claims 1, 4, 5 and 6, wherein ~~a~~ no organic dispersant is ~~not essentially~~ contained therein.

10. (Previously Presented) A manufacturing method for a substrate as an inorganic substrate, comprising polishing the substrate using the abrasive slurry according to claim 9.